

Title (en)

METHOD FOR APPLYING A MATERIAL COMPRISING A STACK WITH ABSORBENT METALLIC LAYER AND DIELECTRIC TOPCOAT, AND THIS MATERIAL

Title (de)

VERFAHREN ZUM AUFBRINGEN EINES MATERIALS MIT EINEM STAPEL MIT ABSORBIERENDER METALLSCHICHT UND DIELEKTRISCHER DECKSCHICHT SOWIE DIESES MATERIAL

Title (fr)

PROCEDE DE DEPOT D'UN MATERIAU COMPORTANT UN EMPILEMENT A COUCHE METALLIQUE ABSORBANTE ET SURCOUCHE DIELECTRIQUE ET CE MATERIAU

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Abstract (en)

[origin: WO2022064129A1] The invention concerns a method for applying a material comprising a substrate (30) coated on one face (29) with a stack of thin layers (14) comprising at least one metallic functional layer (140) and an anti-reflection coating (160) situated above said functional layer (140) on the opposite side from said substrate (30) which finishes with: - a metallic layer (168), said metallic layer (168) having a physical thickness of between 1.0 and 8.0 nm, or even between 1.5 and 5.0 nm, or even between 1.8 and 2.5 nm; and then - a dielectric topcoat (169) which is situated on and in contact with said absorbent metallic layer (168).

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